501786189 01/13/2012

PATENT ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Jun-De Jin	01/13/2012
Tzu-Jin Yeh	01/13/2012

RECEIVING PARTY DATA

Name:	Taiwan Semiconductor Manufacturing Co., Ltd.
Street Address:	No. 8, Li-Hsin Road 6
Internal Address:	Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	13350206

CH $40.00 13350206

CORRESPONDENCE DATA

Fax Number: (215)689-4921
Email: jmgunther@duanemorris.com
Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.
Correspondent Name: Jarrad M. Gunther
Address Line 1: 30 South 17th Street
Address Line 4: Philadelphia, PENNSYLVANIA 19103-4196

ATTORNEY DOCKET NUMBER:	N1085-00914
NAME OF SUBMITTER:	Jarrad M. Gunther

Total Attachments: 2
source=N1085-00914Assignment#page1.tif
source=N1085-00914Assignment#page2.tif

ATTORNEY DOCKET NO.: 2011.1053/1085.914

ASSIGNMENT AND AGREEMENT

For value received, we, **Jun-De JIN and Tzu-Jin YEH,** hereby transfer to **Taiwan Semiconductor Manufacturing Co., Ltd.**, with its principal place of business located at No. 8, Li-Hsin Road 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, Republic of China, and its successors, assigns and legal representatives, the entire right, title and interest, for the United States of America, in and to certain inventions related to **THROUGH-CHIP INTERFACE (TCI) STRUCTURE FOR WIRELESS CHIP-TO-CHIP COMMUNICATION,** described in a non-provisional application and under any and all Letters Patent and any divisions, continuations, continuations-in-part, reexamination certificates, reissues, and extensions thereof, or claiming priority therefrom that may be granted in the United States for said inventions; and we also concurrently hereby sell, assign and transfer to Taiwan Semiconductor Manufacturing Co., Ltd. the entire right, title and interest in and to said inventions for all countries foreign to the United States, including all rights of priority arising from the application aforesaid, and all the rights and privileges under any and all forms of protection, including Letters Patent, that may be granted in said countries foreign to the United States for said inventions.

We authorize Taiwan Semiconductor Manufacturing Co., Ltd. to make application for such protection in its own name and maintain such protection in any and all countries foreign to the United States, and to invoke and claim for any application for patent or other form of protection for said inventions, without further authorization from us, any and all benefits, including the right of priority provided by any and all treaties, conventions, or agreements.

We hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any document which may be required in any country in proof of the right of Taiwan Semiconductor Manufacturing Co., Ltd. to apply for patent or other form of protection for said inventions and to claim the aforesaid benefit of the right of priority.

We request that any and all patents for said inventions be issued to Taiwan Semiconductor Manufacturing Co., Ltd. in the United States and in all countries foreign to the United States, or to such nominees as Taiwan Semiconductor Manufacturing Co., Ltd. may designate.

We agree that, when requested, we shall, without charge to Taiwan Semiconductor Manufacturing Co., Ltd. but at its expense, sign all papers, and do all acts which may be necessary, desirable or convenient in connection with said applications, patents, or other forms of protection.

Inventor No. 1

Dated: 2012/01/13 Jun-De Jin

Jun-De JIN

Residence:

Room 3, 11F., No. 645, Section 2, Kuang-Fu Road, East District, Hsinchu City, Taiwan, R.O.C.

Inventor No. 2

Dated: 2012/01/13 Tzu-Jin Yeh

Tzu-Jin YEH

Residence:

Room 23, 15F., No. 247, Niupu E. Road, Shiangshan District, Hsinchu City 300, Taiwan, R.O.C.